

Final Product/Process Change Notification Document #:FPCN22966ZR Issue Date:08 Nov 2021

Title of Change:	Qualification of Automotive FS3 trench IGBT 12inch Technology at Global Foundries in New York, US for Wafer Fab Capacity Expansion			
Proposed Changed Material First Ship Date:	31 Oct 2022 or earlier if approved by customer			
Current Material Last Order Date:	26 Jul 2022 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.			
Current Material Last Delivery Date:	30 Oct 2022 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory			
Product Category:	Active components – Discrete components			
Contact information:	Contact your local onsemi Sales Office or <u>Bokyun.Seo@onsemi.com</u>			
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order or < <u>PCN.samples@onsemi.com</u> >. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.			
Sample Availability Date:	17 Dec 2021			
PPAP Availability Date:	17 Dec 2021			
Additional Reliability Data:	Contact your local onsemi Sales Office or <u>Byeongyeop.Lee@onsemi.com</u>			
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 ZVEL or earlier upon customer approval or per our signed agreements.			
Change Category				
Category	Type of Change			
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter			
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor			
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.			

Description and Purpose:

This Product Change Notification, is the continuation from IPCN22966ZD, which is intended to increase capacity for onsemi automotive FS3 IGBT technology products by transferring wafer fabrication for these products to the Global Foundries Fab located in New York, US.

The changes include transferring wafer fabrication, back grind and back metal, to Global Foundries, and utilizing 300mm instead of 200mm diameter wafers. And while the assembly location remains unchanged (at onsemi, Suzhou, China), wafer saw and die attach tooling are being updated to accommodate 300mm wafers.



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			Befor	e Change	After Change	9
Wafer Fabrication Site			onsemi Bucheon, Korea,		Global Foundries, US,	
			onsemi	Aizu, Japan	onsemi Bucheon, Korea (200mm), onsemi Aizu, Japan (200mm)	
					300mm (Global Fou	
\ \	Wafer Diameter		200mm (existing sites)	200mm (existing sites)	
, in the second s	Wafer Probe Site		Duch and Kana		Global Foundries, US,	
v	Water Probe Sile		onsemi Bucheon, Korea		onsemi Bucheon, Korea	
Back G	Grind, Back Metal Site		onsemi Bucheon, Korea		Global Foundries, US.	
					onsemi Bucheon, Korea	
There is no chang	ge to the orderable par	t number.				
There is no produ	uct marking change as a	a result of	this change.			
Reason / Motiv	vation for Change:	Source/S	Supply/Capacity Chan	ges Process/Materials Char	nge	
	The device has been qualified and validated based on the same Product Specification. The device has					
	pact on fit, form,				acts can be identified, but due	to testing
function, reliability, product safety or manufacturability:		perform	ed by onsemi in relati	on to the PCN, associated r	isks are verified and excluded.	
		No anticipated impacts.				
Sites Affected:						
onsemi Sites External Foundry/Subcon Sites						
onsemi Aizu, Japan				Global Foundries East Fishkill, New York, United States		
onsemi Bucheon,	, Korea					
Marking of Par	rts/Traceability of					
Marking of Parts/ Traceability of Change:		No change of Marking of Parts / Traceability of Change				
		<u> </u>				
Reliability Data	a Summary:					
OV DEVICE NAM	IE: FGH75T65SHD-F155	. FGH75T(65SHDT-F155. FGH60 ⁻	r65SHD-F155, FGY160T65S	PD-F085	
	78534, U78535, U7853					
PACKAGE: TO24	17					
Test	Specification	n	Condition		Interval	Results
HTRB	JESD22-A108		Ta=175°C, 100_% max rated V		1008 hrs	0/240
HTGB	JESD22-A108		Ta=175°C, 100_% max Vge		1008 hrs	0/240
	HTSL JESD22-A103		Ta=175°C, No bias		1008 hrs	0/240
HISL	TC JESD22-A104		Ta= -55°C to + 150_°C		1000 cyc	0/240
	JESD22-A104			_ 0		
	JESD22-A104 JESD22-A110		130°C, 85% RH, 18	—	96 hrs	0/240
TC)	130°C, 85% RH, 18 130°C, 85% RH, 18	– 3.8psia, bias	96 hrs 96 hrs	0/240 0/240

NOTE: AEC-1pager is attached.

To view attachments:

1. Download pdf copy of the PCN to your computer

2. Open the downloaded pdf copy of the PCN

3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field

4. Then click on the attached file.

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Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle				
AFGY120T65SPD-B4	NA	FGY160T65SPD-F085				
FGY160T65SPD-F085E	NA	FGY160T65SPD-F085				
FGY120T65SPD-F085	NA	FGY160T65SPD-F085				
AFGY160T65SPD-B4	NA	FGY160T65SPD-F085				
FGY160T65SPD-F085	NA	FGY160T65SPD-F085				



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
FGY120T65SPD-F085		FGY160T65SPD-F085	NA	
FGY160T65SPD-F085		FGY160T65SPD-F085	NA	